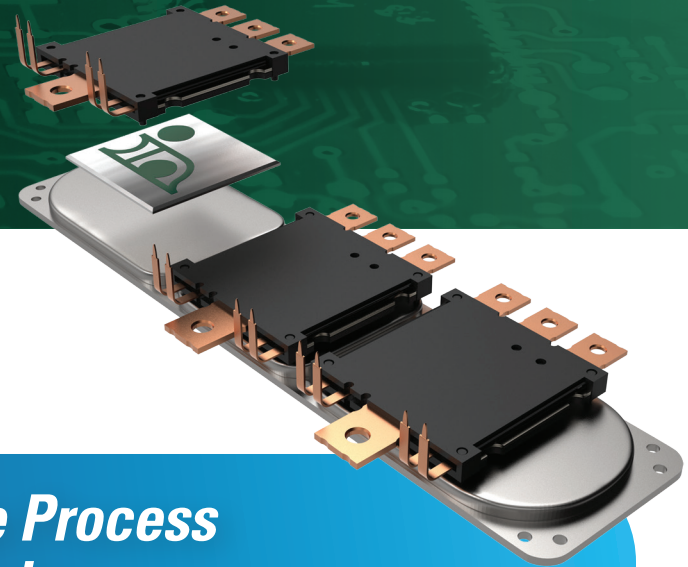


# Indalloy<sup>®</sup> 301 LT



## Package-Attach Solder Preform Technology

*Specifically Designed to Reduce Process  
Temperatures for Power Electronics  
Package-Attach Applications*



Lower Processing  
Temperatures



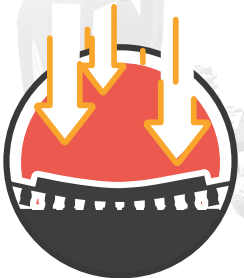
Robust  
Reliability



Solid Thermal  
Performance



Prevents  
Encapsulation  
Breakdown



Prevents  
Warpage



Energy  
Savings

*Available in InFORMS<sup>®</sup>, Preforms, and Ribbon*

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**From One Engineer To Another<sup>®</sup>**

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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